

## STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended :

Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped products should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 24 months after shipment. Extended shelf life over this period require a solderability check before use.

## HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

## PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required.

The rate of preheat should not exceed 3°C per second.

## SOLDERING FLUX

Use mildly activated rosin RA and RMA fluxes, but do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

## SOLDERING TYPE

Lead containing solders, such as Sn60, Sn62 or Sn63 and lead free solders, such as SnAgCu, can all be used with our MLCCs.

In case of non-magnetic termination code "C", use lead containing or lead (Pb)-free SAC405 solders.

## SOLDERING HEIGHT

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less.

(Reference from IPC-610E)

## COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

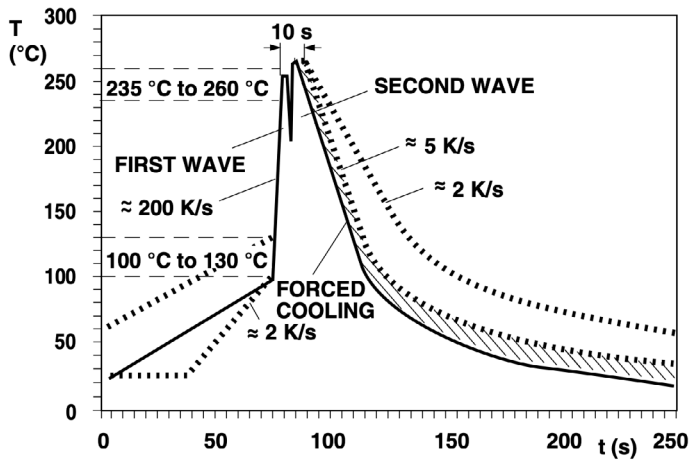
## CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

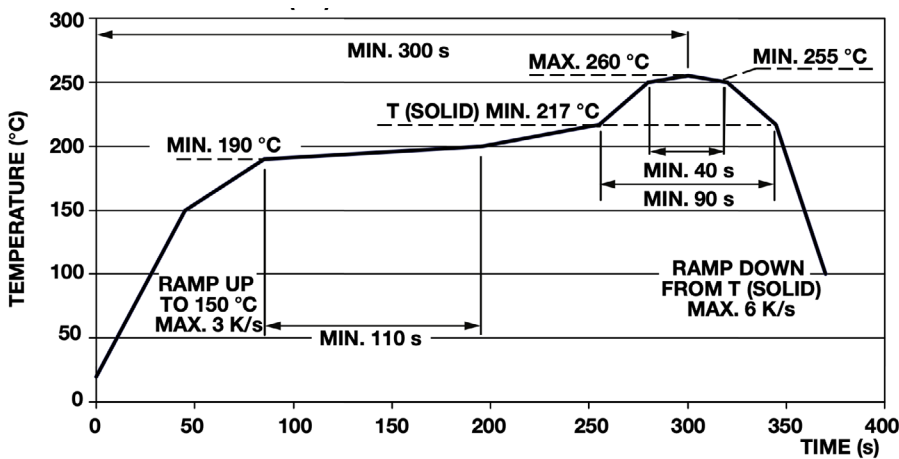
## SOLDERING CONDITIONS

SIZE	THICKNESS	WAVE	REFLOW
0402	All	0	0
0505	All	0	0
0603	All	0	0
0805	< 1.25mm	0	0
0805	≥ 1.25mm		0
1111	< 1.25mm	0	0
1111	≥ 1.25mm		0
1206	< 1.25mm	0	0
1206	≥ 1.25mm		0
1210	< 1.25mm	0	0
1210	≥ 1.25mm		0
larger than 1210	All		0

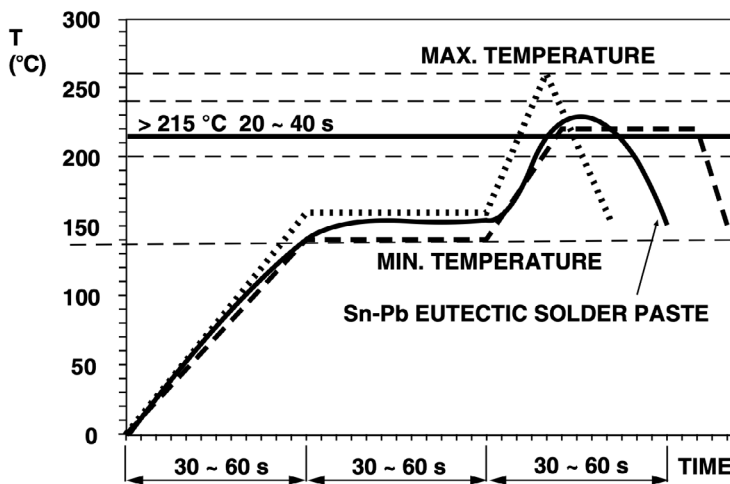
**WAVE SOLDERING PROFILE**



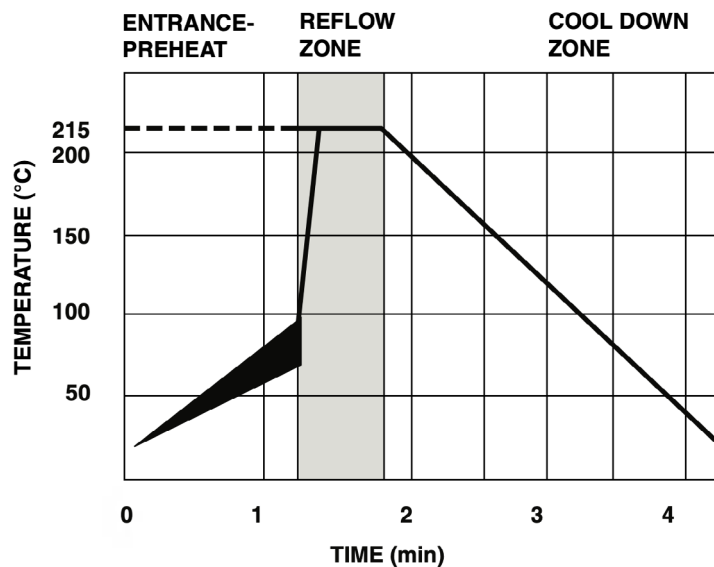
**LEADFREE REFLOW SOLDERING PROFILE**



**SNPB REFLOW SOLDERING PROFILE**



## VAPOUR PHASE REFLOW PROFILE



## HAND SOLDERING

Hand soldering is not recommended as the thermal shock may cause a crack, however if used the following recommendations should be taken :

- Soldering iron tip diameter  $\leq 3.0$  mm and wattage max. 20W.
- The Capacitors shall be pre-heated to 150°C and that the temperature gradient between the devices and the tip of the soldering iron.
- Tip temperature  $\leq 280$ °C and should't be applied for more than 5 seconds.
- The required amount of solder shall be melted on the soldering tip.
- The tip of iron should not contact the ceramic body directly.
- The Capacitors shall be cooled gradually at room temperature after soldering.
- Forced air cooling is not allowed.